TIDA060001 DAC Mode BOM

Comment	Description	Designator	Footprint	Quantity
GRM1885C1H332JA01D	CAP, CERM, 3300 pF, 50 V, +/-	C2	0603	1
GRM188R71C103KA01D	CAP, CERM, 0.01 µF, 16 V, +/-	C4, C13, C14, C19, C20, C21	0603	6
GRM1885C1H561JA01D	CAP, CERM, 560 pF, 50 V, +/-	C5	0603	1
06035A271JAT2A	CAP, CERM, 270 pF, 50 V, +/-	C6	0603	1
UMK107AB7105KA-T	CAP, CERM, 1 µF, 50 V, +/- 10	C7, C9	0603	2
GRM188R71C102KA01D	CAP, CERM, 1000 pF, 16 V, +/-	C8, C10	0603	2
160R07X104KV4T	CAP, CERM, 0.1 µF, 16 V, +/- 1	C11, C12, C18	0402_065	3
GRT188R61E106ME13D	CAP, CERM, 10 µF, 25 V, +/- 2	C15, C22	0603	2
JMK212BJ476MG-T	CAP, CERM, 47 µF, 6.3 V, +/- 2	C16	0805_HV	1
0603YC104JAT2A	CAP, CERM, 0.1 µF, 16 V, +/- 5	C17	0603	1
GCM188R71H103KA37D	CAP, CERM, 0.01 µF, 50 V, +/-	C23	0603	1
06035C333JAT2A	CAP, CERM, 0.033 µF, 50 V, +/	C24	0603	1
GRM188R71H223KA01D	CAP, CERM, 0.022 µF, 50 V, +/	C25	0603	1
06035A102KAT2A	CAP, CERM, 1000 pF, 50 V, +/-	C26	0603	1
GRT31CR61H106KE01L	CAP, CERM, 10 µF, 50 V, +/- 1	C27	1206_180	1
GRM31MR71E225KA93L	CAP, CERM, 2.2 µF, 25 V, +/- 1	Cin1	1206	1
GRM21BR60J226ME39L	CAP, CERM, 22 µF, 6.3 V, +/- 2	Cout1	0805_HV	1
1SMB5931BT3G	Diode, Zener, 18 V, 550 mW, S	D1	SMB	1
150060BS75000	LED, Blue, SMD	D2	LTST-C193_Blue	1
150060RS75000	LED, Red, SMD	D3	LTST-C191_Red	1
Fiducial	Fiducial mark. There is nothin	FID4, FID5, FID6	Fiducial10-30	3
SSQ-110-03-T-D	Receptacle, 2.54mm, 10x2, Tin	J1	BoosterPack_40pin_J1J3	1
SSQ-110-03-T-D	Receptacle, 2.54mm, 10x2, Tin	J2	BoosterPack_40pin_J2J4	1
961102-6404-AR	Header, 2.54mm, 2x1, TH	J3	3M_961102-6404-AR	1
39357-0002	Terminal Block, 3.5 mm, 2x1, T	J4	Molex_39357-0002	1
LPS4018-103MRB	Inductor, Shielded Drum Core,	L1	LPS4018	1
DO1608C-334MLB	Inductor, Drum Core, Ferrite, 3	L2	DO1608C	1
DO1608C-474MLB	Inductor, Drum Core, Ferrite, 4	L3	DO1608C	1
LQH2MCN1R0M52	Inductor, Wirewound, Ferrite,	L4	LQH2MC_52	1
Size: 0.65" x 0.20 "	Thermal Transfer Printable Lab	LBL1	Label_650x200	1
CRCW040210K0FKED	RES, 10.0 k, 1%, 0.063 W, 0402	R3, R4, R5, R6, R13, R14, R17	0402	7
CRCW06030000Z0EA	RES, 0, 5%, 0.1 W, 0603	R7, R10, R11, R20, R24, R25	0603	6
CRCW040233K0JNED	RES, 33 k, 5%, 0.063 W, 0402	R15	0402	1
CRCW0402330RJNED	RES, 330, 5%, 0.063 W, 0402	R16	0402	1
CRCW0603680RJNEA	RES, 680, 5%, 0.1 W, 0603	R18, R19	0603	2
CRCW0603150RFKEA	RES, 150, 1%, 0.1 W, 0603	R22, R23	0603	2
ERJ-6GEYJ4R7V	RES, 4.7, 5%, 0.125 W, 0805	R26	0805_HV	1
RC0603FR-07100KL	RES, 100 k, 1%, 0.1 W, 0603	R27, R28	0603	2
ERJ-2RKF1000X	RES, 100, 1%, 0.1 W, 0402	Rpg1	0402	1
AFE031AIRGZT	Powerline Communications A	U1	RGZ0048B - Thicker Vias	1
TPS62177DQCR	28V, 0.5A Step-Down Convert	U2	DQC0010A-Edited	1
SN74LVC2G07DBVR	Dual Buffer/Driver with Open-	U3	DBV0006A_N	1
B350A-13-F	Diode, Schottky, 50 V, 3 A, SM	U4, U5, U6, U8	SMA	4

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